

Table 1. Available Options⁽¹⁾⁽²⁾

Device	BSL	EEM	Flash (KB)	RAM (B)	Timer_A	COMP_A+ Channel	ADC10 Channel	USCI_A0, USCI_B0	Clock	I/O	Package Type
MSP430G2553IRHB32	1	1	16	512	2x TA3	8	8	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2453IRHB32	1	1	8	512	2x TA3	8	8	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2353IRHB32	1	1	4	256	2x TA3	8	8	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2253IRHB32	1	1	2	256	2x TA3	8	8	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2153IRHB32	1	1	1	256	2x TA3	8	8	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2513IRHB32	1	1	16	512	2x TA3	8	-	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2413IRHB32	1	1	8	512	2x TA3	8	-	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2313IRHB32	1	1	4	256	2x TA3	8	-	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	
MSP430G2213IRHB32	1	1	2	256	2x TA3	8	-	1	LF, DCO, VLO	24	32-QFN
24										28-TSSOP	
16										20-TSSOP	
16										20-PDIP	

- (1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.
- (2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.